24-Pin XOR AmPAL20XRP10 Family

24-Pin IMOX™ Programmable Array Logic (PAL) Elements

Distinctive Characteristics

- AND-OR-XOR logic structure
- AMD's superior IMOX technology
  - Guarantees t_{PD} = 20 ns max
- Individually programmable output polarity on each output
- Eight logical product terms per output
- Programming yields > 98% are realized via platinum-silicide fuse technology and the use of added test words
- Post Programming Functional Yield (PPFY) of 99.9%
- PRELOAD feature permits full logical verification
- Reliability assured through more than 70 billion fuse hours of life testing with no failures
- AC and DC parametric testing at the factory through on-board testing circuitry
- > 3000V ESD protection per pin
- JEDEC-Standard LCC and PLCC pinout

General Description

AMD 24-pin XOR PAL devices are high-speed, electrically programmable array logic elements. They utilize the familiar sum-of-products (AND-OR-XOR) structure allowing users to program custom logic functions to fit most applications precisely. Typically they are a replacement for low-power Schottky SSI/MSI logic circuits that require an exclusive-OR function, reducing chip count by more than 5 to 1 and greatly simplifying prototyping and board layout.

Five different devices are available, including both registered and combinatorial devices. All devices have user-programmable output polarity on all outputs. A variety of speed options allow the designer maximum flexibility in matching precise system requirements. The Product Selector Guide below shows the available speed options. The second table gives details about the functionality of the five available devices.

Please see the following pages for Block Diagrams.

Product Selector Guide

AMD PAL Speed/Power Families

Family	t_{PD} ns (Max.)		t_S ns (Min.)		t_{CO} ns (Max.)		I_{CC} mA (Max.)	I_{OL} mA (Min.)	
	C Devices	M Devices	C Devices	M Devices	C Devices	M Devices	C/M Devices	C Devices	M Devices
Very High-Speed (-20 & -25) Versions	20	25	20	25	13	15	210	24	12
High-Speed (-30 & -35) Versions	30	35	30	35	15	25	180	24	12
High-Speed, Half-Power (-30L & -35L) Versions	30	35	30	35	15	25	105	24	12
Half-Power (-40L & -45L) Versions	40	45	40	45	30	35	105	24	12

Part Number	Array Inputs	Logic	Output Enable	Outputs/Polarity	Package Pins
22XP10	12 Dedicated, 10 Bidirectional	Ten (2-6)-Wide AND-OR-XOR	Programmable	Bidirectional/Programmable	24
20XRP4	10 Dedicated, 4 Feedback, 6 Bidirectional	Four (2-6)-Wide AND-OR-XOR	Dedicated	Registered/Programmable	24
		Six 8-Wide AND-OR	Programmable	Bidirectional/Programmable	
20XRP6	10 Dedicated, 6 Feedback, 4 Bidirectional	Six (2-6)-Wide AND-OR-XOR	Dedicated	Registered/Programmable	24
		Four 8-Wide AND-OR	Programmable	Bidirectional/Programmable	
20XRP8	10 Dedicated, 8 Feedback, 2 Bidirectional	Eight (2-6)-Wide AND-OR-XOR	Dedicated	Registered/Programmable	24
		Two 8-Wide AND-OR	Programmable	Bidirectional/Programmable	
20XRP10	10 Dedicated, 10 Feedback	Ten (2-6)-Wide AND-OR-XOR	Dedicated	Registered/Programmable	24

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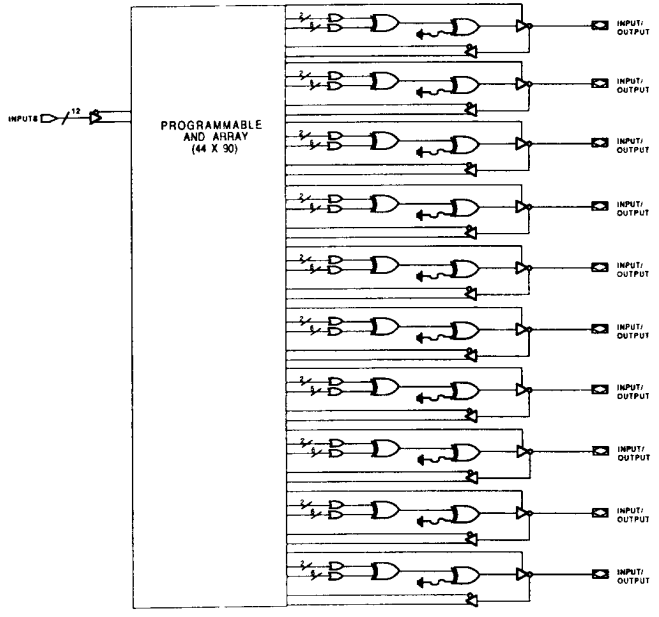
Block Diagrams

AmPAL22XP10



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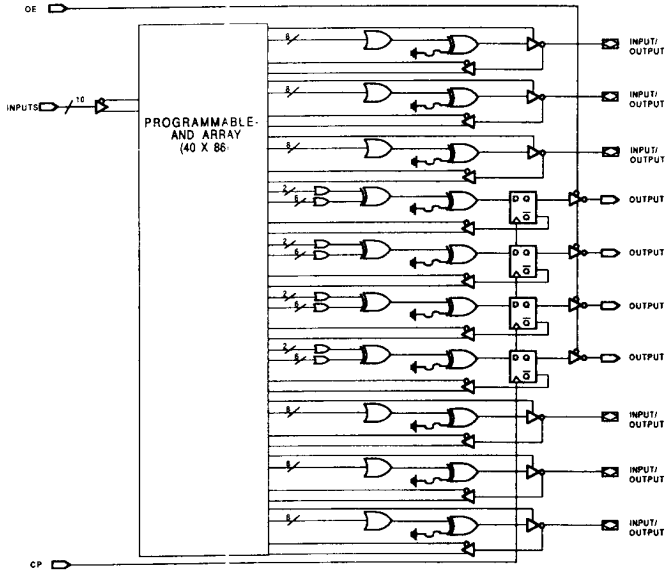
AmPAL20XRP4



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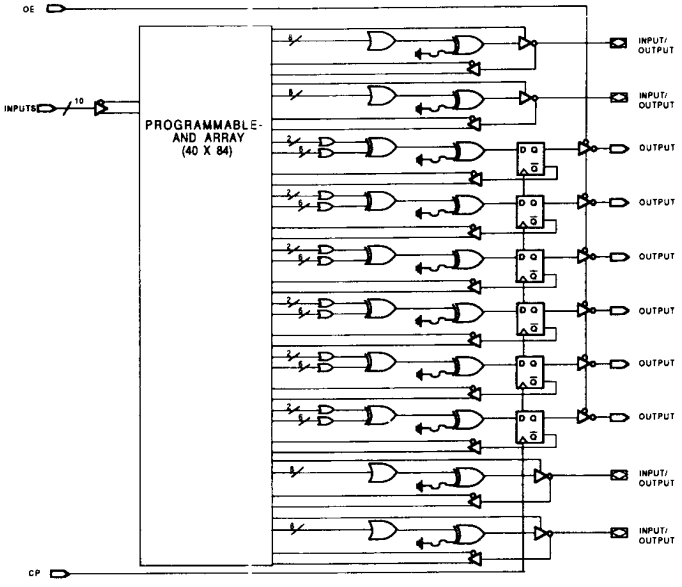
Block Diagrams (Cont'd.)

AmPAL20XRP6



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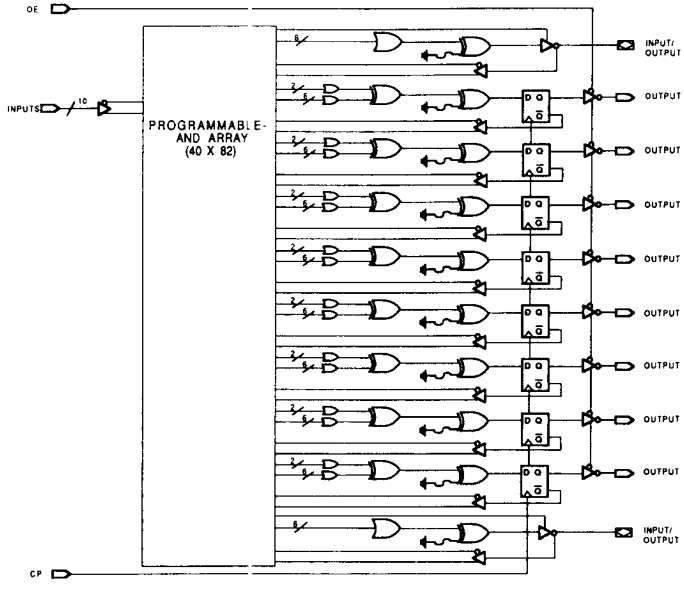
AmPAL20XRP8



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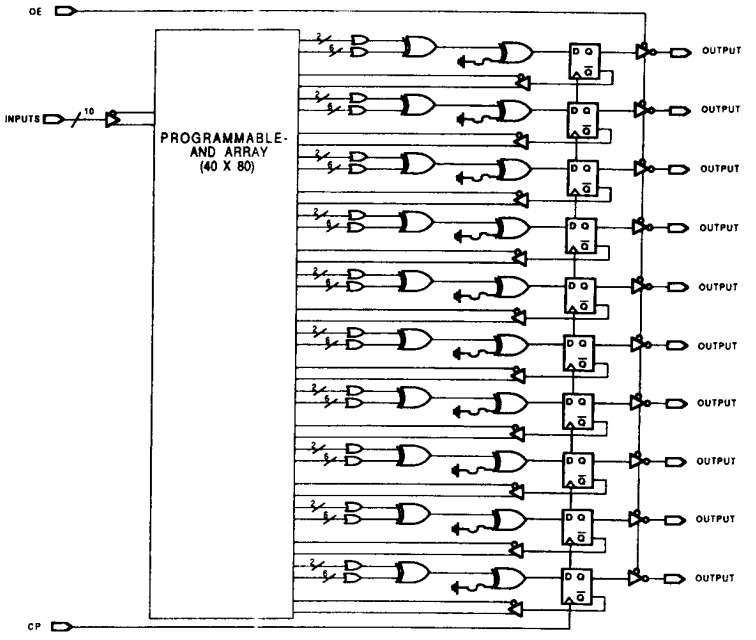
Block Diagrams (Cont'd.)

AmPAL20XRP10



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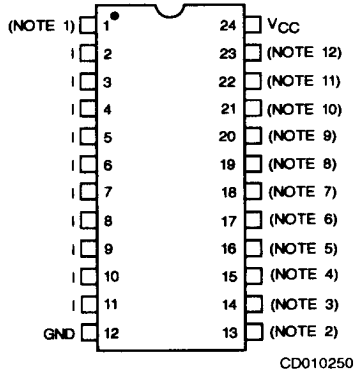
Connection Diagrams

Top View

DIPs*



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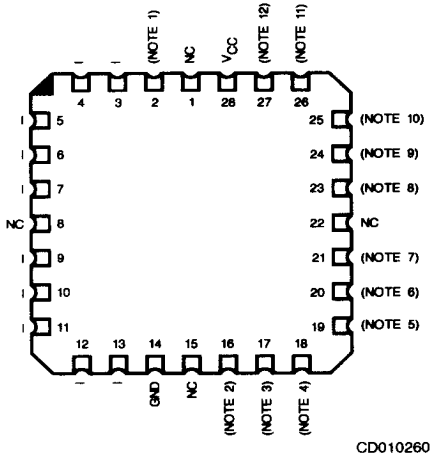
LCC**



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Note: Pin 1 is marked for orientation.

Notes:

	22XP10	20XRP4	20XRP6	20XRP8	20XRP10
1	I	CLK	CLK	CLK	CLK
2	I	OE	OE	OE	OE
3	I/O	I/O	I/O	I/O	O
4	I/O	I/O	I/O	O	O
5	I/O	I/O	O	O	O
6	I/O	O	O	O	O
7	I/O	O	O	O	O
8	I/O	O	O	O	O
9	I/O	O	O	O	O
10	I/O	I/O	O	O	O
11	I/O	I/O	I/O	O	O
12	I/O	I/O	I/O	I/O	O

*Also available in 24-Pin Ceramic Flatpack. Pinouts identical to DIPs.
**Also available in 28-Pin Plastic Leaded Chip Carrier. Pinouts identical to LCC.

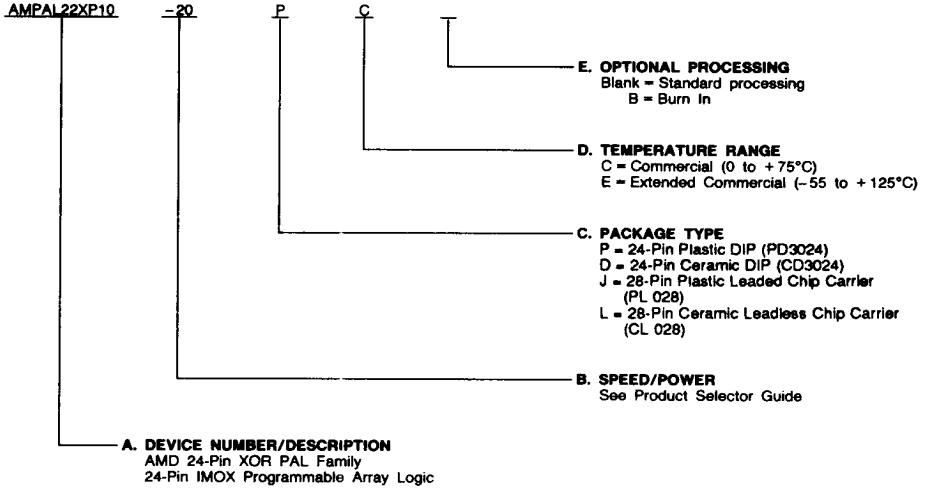
Pin Designations

I = Input
I/O = Input/Output
O = Output
V_{CC} = Supply Voltage
GND = Ground
CLK = Clock
OE = Output Enable
NC = No Connect

Ordering Information

Standard Products

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of: **A. Device Number**
B. Speed Option (if applicable)
C. Package Type
D. Temperature Range
E. Optional Processing



Valid Combinations	
AMPAL22XP10-20/-30/-30L/-40L	PC, DC, DCB, DE, JC, LC, LE
AMPAL20XRP4-20/-30/-30L/-40L	
AMPAL20XRP6-20/-30/-30L/-40L	
AMPAL20XRP8-20/-30/-30L/-40L	
AMPAL20XRP10-20/-30/-30L/-40L	

Valid Combinations

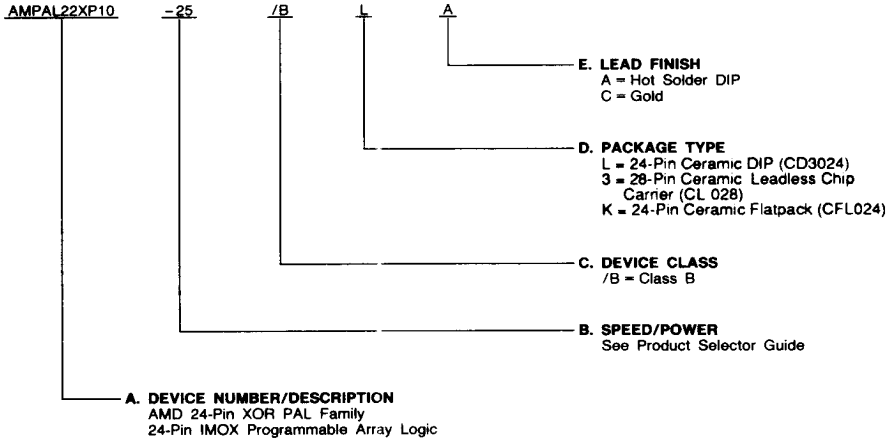
Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released combinations, and to obtain additional data on AMD's standard military grade products.

Ordering Information (Cont'd.)

APL Products

AMD products for Aereospace and Defense applications are available in several packages and operating ranges. APL (Approved Products List) products are fully compliant with MIL-STD-883C requirements. The order number (Valid Combination) for APL products is formed by a combination of:

A. Device Number
B. Speed Option (if applicable)
C. Device Class
D. Package Type
E. Lead Finish



Valid Combinations	
AMPAL22XP10-25/-35/-35L/-45L	/BLA, /B3A, /BKA
AMPAL20XRP4-25/-35/-35L/-45L	
AMPAL20XRP6-25/-35/-35L/-45L	
AMPAL20XRP8-25/-35/-35L/-45L	
AMPAL20XRP10-25/-35/-35L/-45L	

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations or to check for newly released valid combinations.

Group A Tests

Group A tests consist of Subgroups 1, 2, 3, 7, 8, 9, 10, & 11

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Functional Description

AMD 24-PIN XOR PAL20XRP10 Family Characteristics

All members of the AMD 24-Pin XOR PAL Family have common electrical characteristics and programming procedures. All parts are produced with a fusible link at each input to the AND gate array, and connections may be selectively removed by applying appropriate voltages to the circuit.

Initially the AND gates are connected, via fuses, to both the true and complement of each input. By selective programming of fuses the AND gates may be "connected" to only the true input (by blowing the complement fuse), to only the complement input (by blowing the true fuse), or to neither type of input (by blowing both fuses) establishing a logical "don't care." When both the true and complement fuses are left intact a logical false results on the output of the AND gate, while all fuses blown results in a logical true state. On the AmPAL22XP10 device, the AND gates are connected to fixed (2-6) OR-XOR structures whose outputs become device outputs. The remaining four (registered) devices function as follows: for combinatorial outputs, the AND gates are connected to fixed-OR gates whose outputs become device outputs. For registered outputs, the AND gates are connected to fixed (2-6) OR-XOR structures whose outputs become output register inputs.

All parts are fabricated with AMD's fast programming, highly reliable Platinum-Silicide Fuse technology. Utilizing an easily implemented programming algorithm, these products can be rapidly programmed to any customized pattern. Extra test words are pre-programmed during manufacturing to insure extremely high field programming yields (> 98%), and provide extra test paths to achieve excellent parametric correlation.

Power-Up Reset

The registered devices in the AMD PAL family have been designed to reset during system power-up. Following power-up, all registers will be initialized to zero, setting all the outputs to a logic 1. This feature provides extra flexibility to the designer and is especially valuable in simplifying state machine initialization.

PRELOAD

AMD PAL devices are designed with unique PRELOAD circuitry that provides an easy method of testing registered devices for logical functionality. PRELOAD allows any arbitrary state value to be loaded into the registered output of an AMD PAL device.

A typical functional test sequence would be to verify all possible state transitions for the device being tested. This requires the ability to set the state registers into an arbitrary "present state" value and to set the device inputs to any arbitrary "present input" value. Once this is done, the state machine is clocked into a new state or "next state." The next state is then checked to validate the transition from the present state. In this way any state transition can be checked.

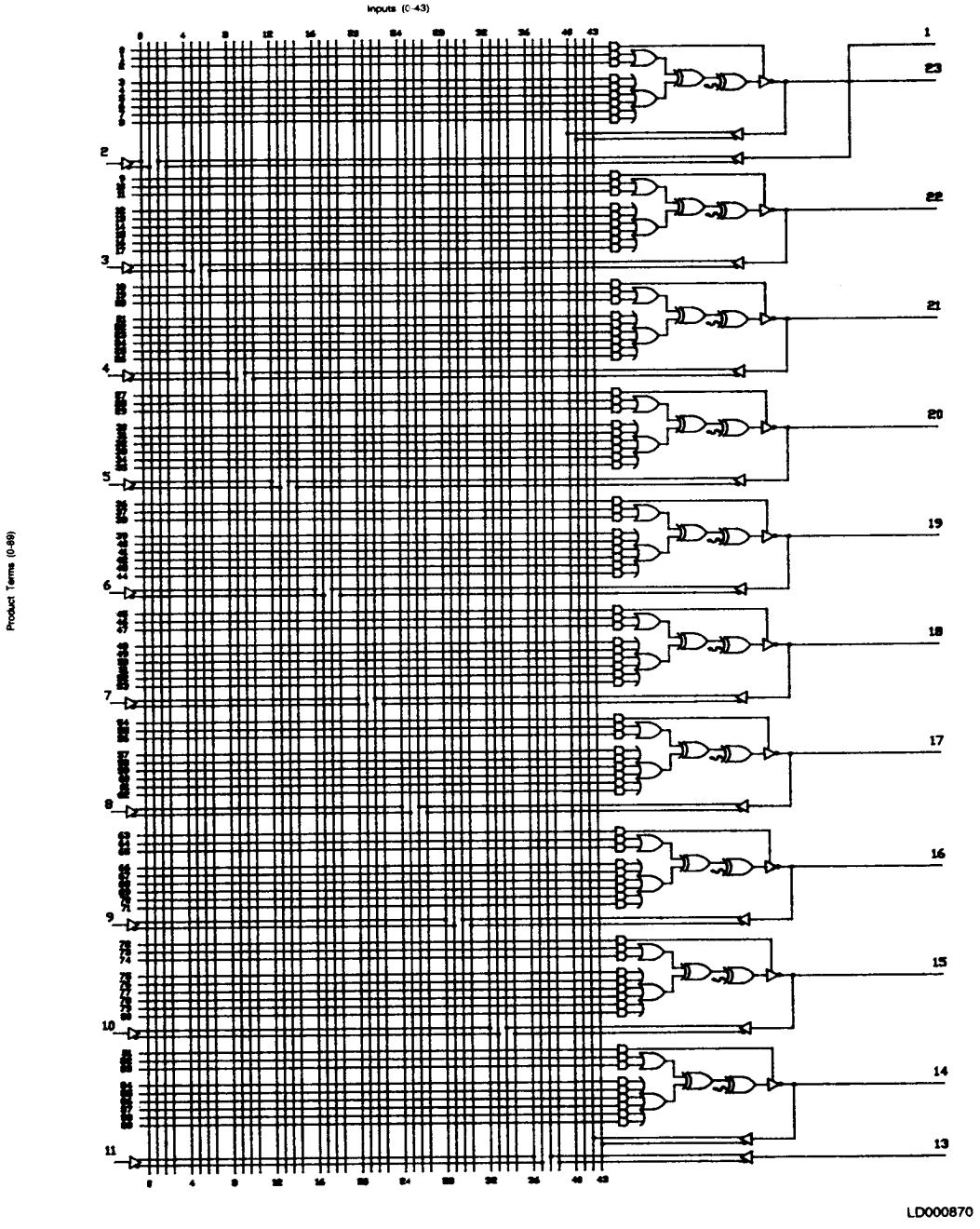


Figure 1. AmPAL22XP10 Logic Diagram

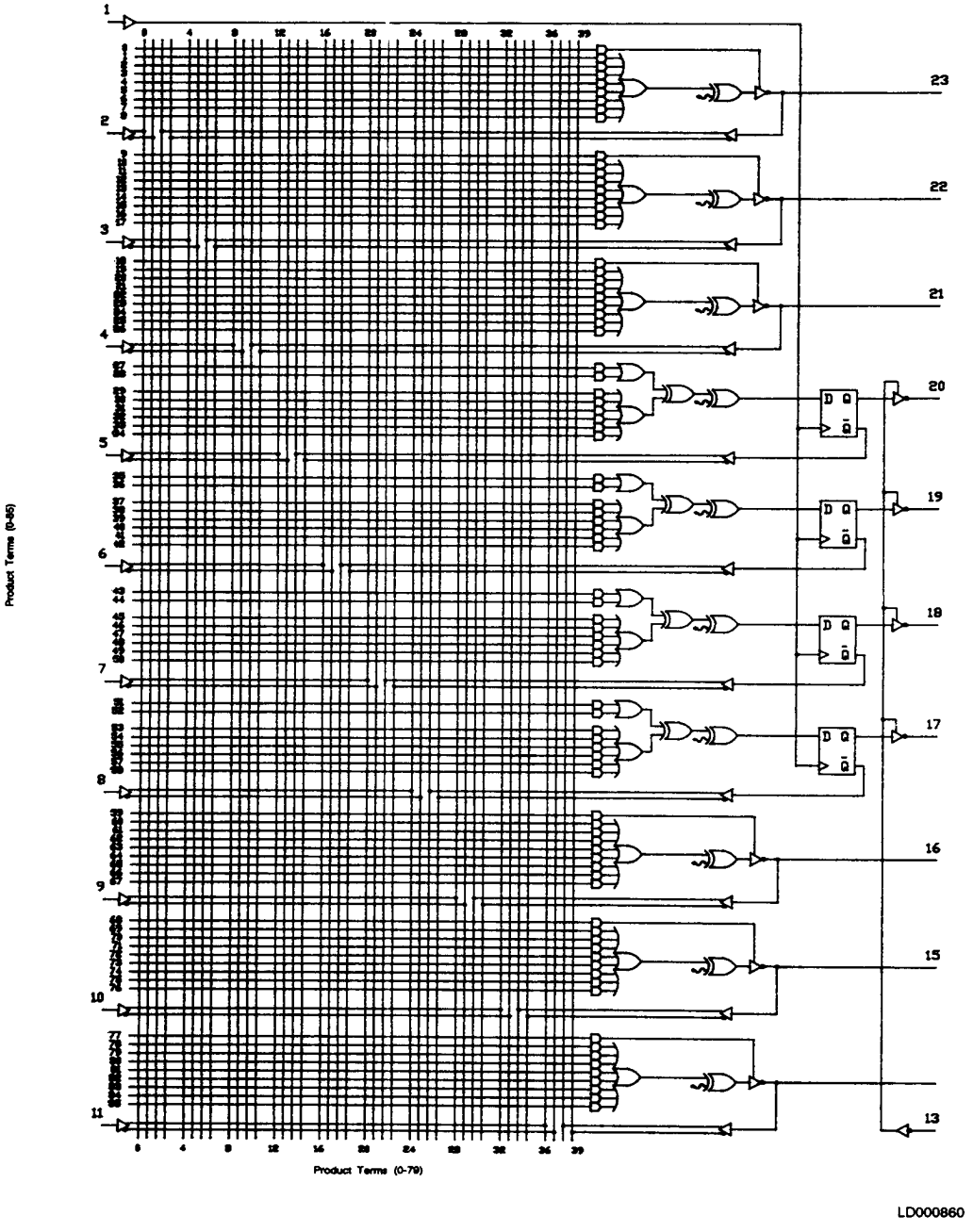


Figure 2. AmPAL20XRP4 Logic Diagram

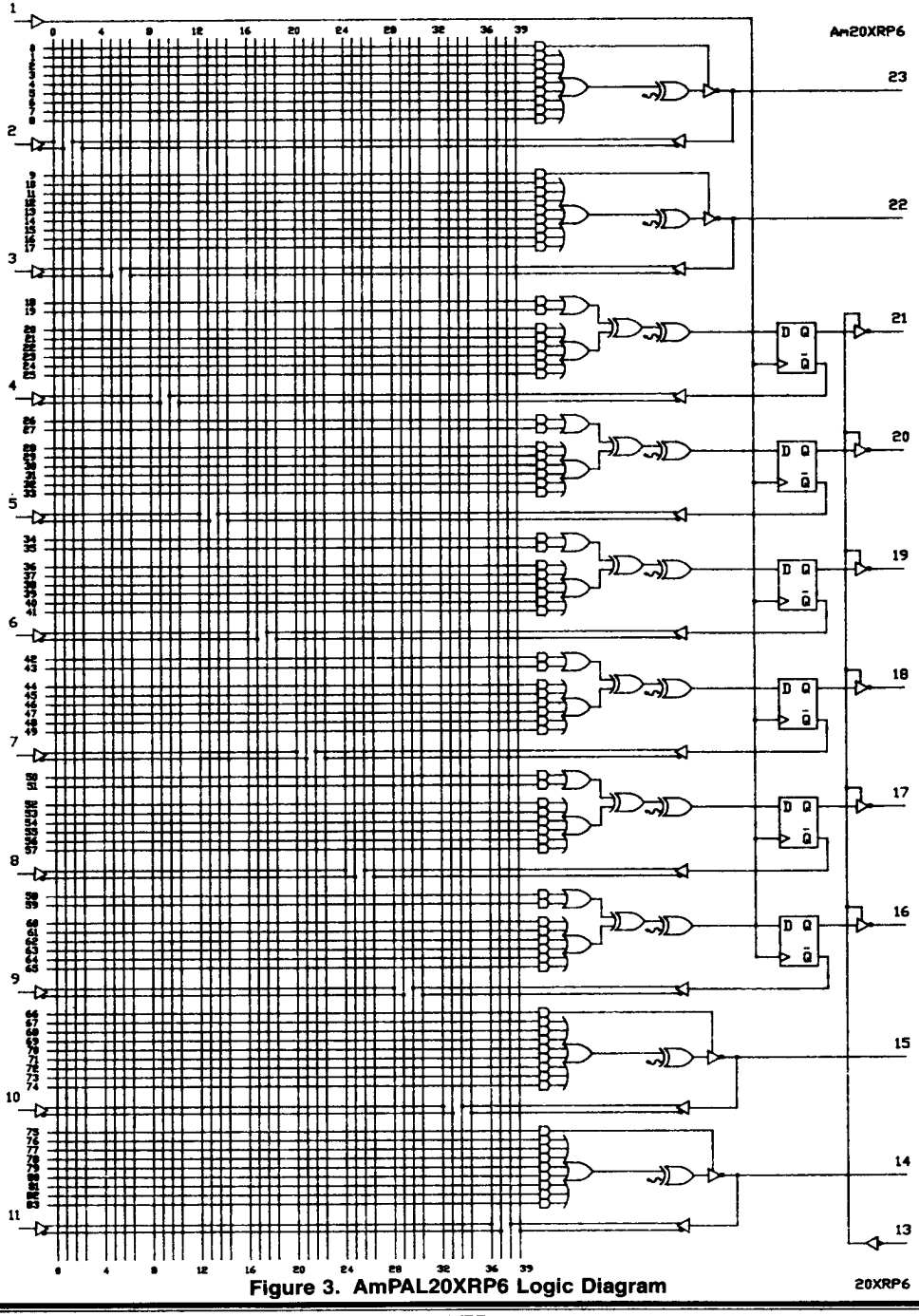


Figure 3. AmPAL20XRP6 Logic Diagram

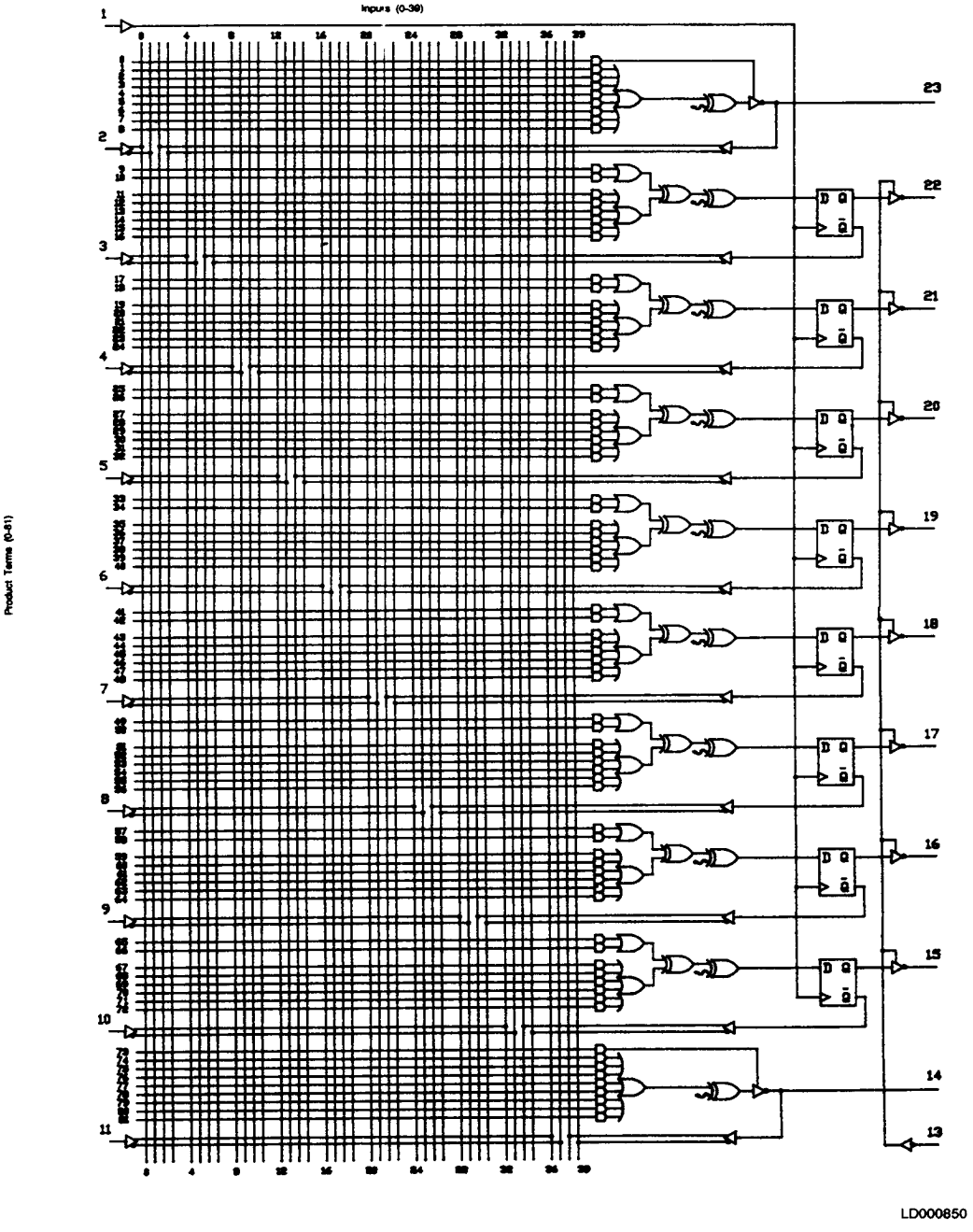


Figure 4. AmPAL20XRP8 Logic Diagram

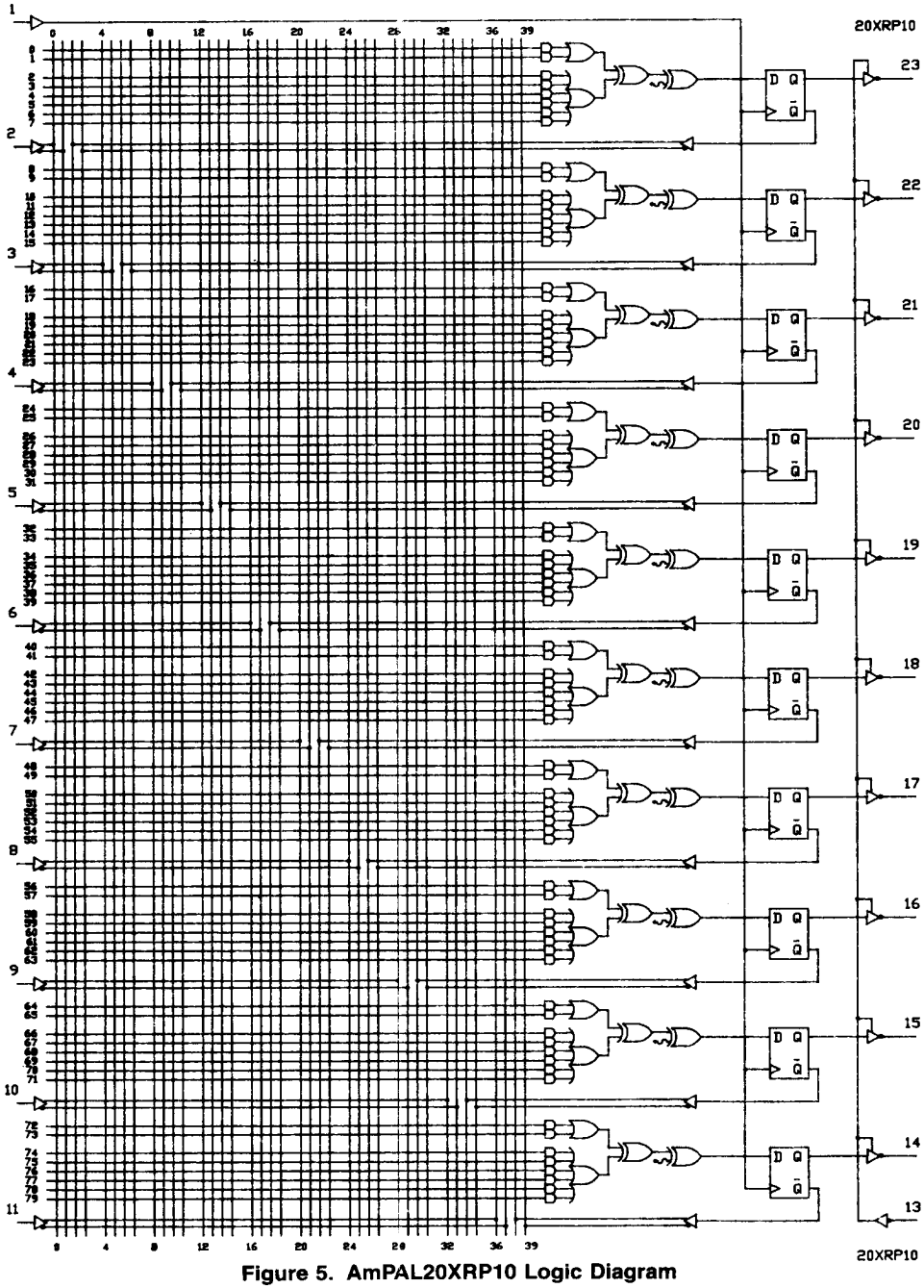
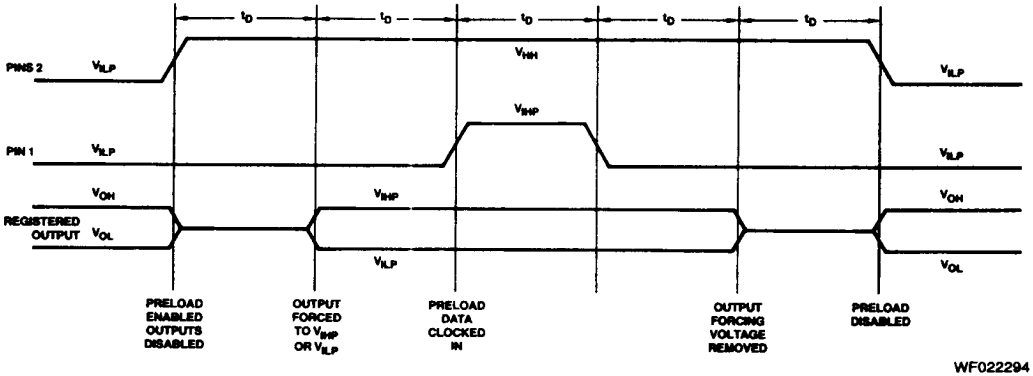


Figure 5. AmPAL20XRP10 Logic Diagram

PRELOAD of Registered Outputs

The AMD 24-pin XOR PAL devices incorporate circuitry to allow loading each register synchronously to either a HIGH or LOW state. This feature simplifies testing since any initial state for the registers can be set to optimize test sequencing.

The pin levels and timing necessary to perform the PRELOAD function are detailed below:



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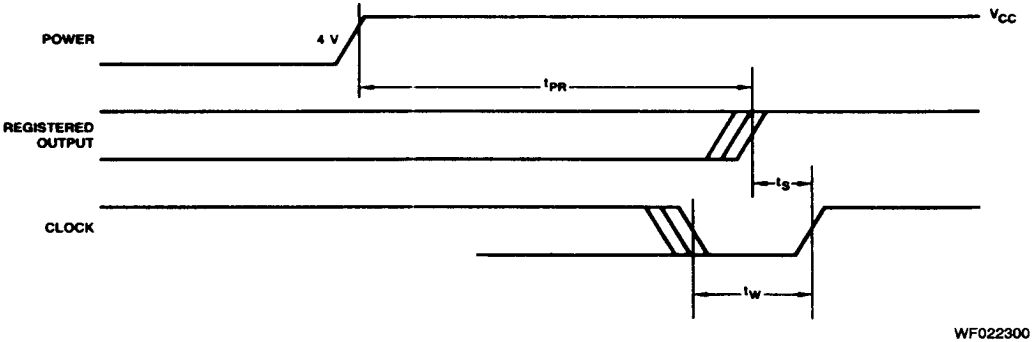
Par.	Min.	Max.
V_{HH}	10	12
V_{ILP}	0	0.5
V_{IHP}	2.4	5.5

Level forced on registered output pin during PRELOAD cycle	Register Q output state after cycle
V_{IHP}	HIGH
V_{ILP}	LOW

Power-Up Reset

The registered devices in the AMD 24-Pin XOR PAL Family have been designed with the capability to reset during system power-up. Following power-up, all registers will be reset to LOW. The output state will be HIGH. This feature provides flexibility to the designer and is especially valuable in simplifying state-machine initialization. A timing diagram and parameter table are shown below. Due to the asynchronous operation of the power-up RESET and the wide range of ways V_{CC} can rise to its steady state, two conditions are required to ensure a valid power-up RESET. These conditions are:

1. The V_{CC} rise must be monotonic.
2. Following reset, the clock input must not be driven from LOW to HIGH until all applicable input and feedback setup times are met.



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Parameters	Description	Min.	Typ.	Max.	Units
t_{PR}	Power-Up Reset Time		600	1000	ns
t_S	Input or Feedback Setup Time	See Switching Characteristics			
t_W	Clock Width				

Absolute Maximum Ratings

Storage Temperature ..... −65 to +150°C
Supply Voltage to Ground Potential
(Pin 24 to Pin 12) Continuous ..... −0.5 to +7.0 V
DC Voltage Applied to Outputs
(Except During Programming).....−0.5 V to +V_{CC} Max.
DC Voltage Applied to Outputs
During Programming ..... 16 V
Output Current Into Outputs During
Programming (Max Duration of 1 sec) ..... 200 mA
DC Input Voltage ..... −0.5 to +5.5 V
DC Input Current ..... −30 to +5 mA

Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

Operating Ranges

Commercial (C) Devices
Temperature (T_A) ..... 0 to +75°C
Supply Voltage (V_{CC}) ..... +4.75 to +5.25 V

Extended Commercial (E) Devices
Temperature (T_A) ..... −55°C Min.
Temperature (T_C) ..... +125°C Max.
Supply Voltage (V_{CC}) ..... +4.50 to +5.50 V

Military (M) Devices*
Temperature (T_A) ..... −55°C Min.
Temperature (T_C) ..... +125°C Max.
Supply Voltage (V_{CC}) ..... +4.50 to +5.50 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

*Military product 100% tested at T_C = +25°C, +125°C, and −55°C.

DC Characteristics over operating range unless otherwise specified; included in Group A, Subgroup 1, 2, 3 tests unless otherwise noted

Parameter Symbol	Parameter Description	Test Conditions			Min.	Typ. (Note 1)	Max.	Units
V_{OH}	Output HIGH Voltage	V_{CC} = Min., V_{IN} = V_{IH} or V_{IL}	I_{OH} = −3.2 mA	COM'L	2.4	3.5		V
			I_{OH} = −2 mA	MIL				
V_{OL}	Output LOW Voltage	V_{CC} = Min., V_{IN} = V_{IH} or V_{IL}	I_{OL} = 24 mA	COM'L			0.5	V
			I_{OL} = 12 mA	MIL				
V_{IH} (Note 2)	Input HIGH Level	Guaranteed Input Logical HIGH Voltage for All Inputs			2.0		5.5	V
V_{IL} (Note 2)	Input LOW Level	Guaranteed Input Logical LOW Voltage for All Inputs					0.8	V
I_{IL}	Input LOW Current	V_{CC} = Max., V_{IN} = 0.40 V				−20	−100	μA
I_{IH}	Input HIGH Current	V_{CC} = Max., V_{IN} = 2.7 V					25	μA
I_I	Input HIGH Current	V_{CC} = Max., V_{IN} = 5.5 V					1.0	mA
I_{SC}	Output Short-Circuit Current	V_{CC} = Max., V_{OUT} = 0.5 V (Note 3)			−30	−60	−90	mA
I_{CC}	Power Supply Current	V_{CC} = Max.	COM'L	MIL				mA
			−20	−25			210	
			−30,	−35,			180	
			−30L, −40L	−35L, −45L			105	
V_I	Input Clamp Voltage	V_{CC} = Min., I_{IN} = −18 mA				−0.9	−1.2	V
I_{OZH}	Output Leakage Current (Note 4)	V_{CC} = Max., V_{IN} = V_{IH} or V_{IL}	V_O = 2.7 V				100	μA
I_{OZL}			V_O = 0.4 V				−100	

Notes: 1. Typical limits are at V_{CC} = 5.0 V and T_A = 25°C.
2. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
3. Not more than one output should be tested at a time. Duration of the short circuit should not be more than one second. V_{OUT} = 0.5V has been chosen to avoid test problems caused by tester ground degradation.
4. I/O pin leakage is the worst case of I_{OZX} or I_{IX} (where X = H or L).

Capacitance*

Parameter Symbol	Parameter Description	Test Conditions		Typ.	Units
C_{IN}	Input Capacitance	V_{IN} = 2.0 V @ f = 1 MHz	Pins 1, 13	11	pF
			Others	6	
C_{OUT}	Output Capacitance	V_{OUT} = 2.0 V @ f = 1 MHz		9	

*These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.

Switching Characteristics

over operating range unless otherwise specified; included in Group A, Subgroup 9, 10, 11 tests unless otherwise noted

Commercial Range

No.	Parameter Symbol	Parameter Description	-20 Version			-30 & -30L Version			-40L Version			Units
			Min.	Typ. (Note 1)	Max.	Min.	Typ. (Note 1)	Max.	Min.	Typ. (Note 1)	Max.	
1	t_{PD}	Input or Feedback to Non-Registered Output 22XP10, 20XRP4, 20XRP6, 20XRP8			20			30			40	ns
2	t_{EA}	Input to Output Enable 22XP10, 20XRP4, 20XRP6, 20XRP8			20			30			40	ns
3	t_{ER}	Input to Output Disable 22XP10, 20XRP4, 20XRP6, 20XRP8			20			30			40	ns
4	t_{PZX}	Pin 13 to Output Enable 20XRP4, 20XRP6, 20XRP8, 20XRP10			15			20			35	ns
5	t_{PXZ}	Pin 13 to Output Disable 20XRP4, 20XRP6, 20XRP8, 20XRP10			15			20			35	ns
6	t_{CO}	Clock to Output 20XRP4, 20XRP6, 20XRP8, 20XRP10			13			15			30	ns
7	t_S	Input or Feedback Setup Time 20XRP4, 20XRP6, 20XRP8, 20XRP10	20			30			40			ns
8	t_H	Hold Time 20XRP4, 20XRP6, 20XRP8, 20XRP10	0			0			0			ns
9	t_P	Clock Period ($t_S + t_{CO}$)	33			45			70			ns
10	t_W	Clock Width	10			15			25			ns
11	$f_{MAX.}$	Maximum Frequency			30.3			22.2			14.3	MHz

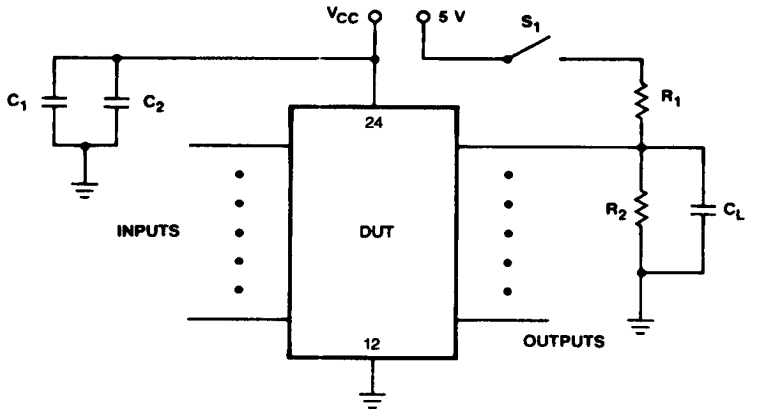
Notes:
1. Typical limits are at $V_{CC} = 5.0$ V and $T_A = 25°C$.
2. t_{PD} is tested with switch S_1 closed and $C_L = 50$ pF.
3. For three-state outputs, output enable times are tested with $C_L = 50$ pF to the 1.5 V level; S_1 is open for high impedance to HIGH tests and closed for high impedance to LOW tests. Output disable times are tested with $C_L = 5$ pF. HIGH to high impedance tests are made to an output voltage of $V_{OH} - 0.5$ V with S_1 open; LOW to high impedance tests are made to the $V_{OL} + 0.5$ V level with S_1 closed.

Military Range

No.	Parameter Symbol	Parameter Description	-25 Version			-35 & -35L Version			-45L Version			Units
			Min.	Typ. (Note 1)	Max.	Min.	Typ. (Note 1)	Max.	Min.	Typ. (Note 1)	Max.	
1	t_{PD}	Input or Feedback to Non-Registered Output 22XP10, 20XRP4, 20XRP6, 20XRP8			25			35			45	ns
2	t_{EA}	Input to Output Enable 22XP10, 20XRP4, 20XRP6, 20XRP8			25			35			45	ns
3	t_{ER}	Input to Output Disable 22XP10, 20XRP4, 20XRP6, 20XRP8			25			35			45	ns
4	t_{PZX}	Pin 13 to Output Enable 20XRP4, 20XRP6, 20XRP8, 20XRP10			20			25			40	ns
5	t_{PXZ}	Pin 13 to Output Disable 20XRP4, 20XRP6, 20XRP8, 20XRP10			20			25			40	ns
6	t_{CO}	Clock to Output 20XRP4, 20XRP6, 20XRP8, 20XRP10			15			25			35	ns
7	t_S	Input or Feedback Setup Time 20XRP4, 20XRP6, 20XRP8, 20XRP10	25			35			45			ns
8	t_H	Hold Time 20XRP4, 20XRP6, 20XRP8, 20XRP10	0			0			0			ns
9	t_P	Clock Period ($t_S + t_{CO}$)	40			60			80			ns
10	t_W	Clock Width	12			20			30			ns
11	$f_{MAX.}$	Maximum Frequency			25			16.7			12.5	MHz

Notes:
1. Typical limits are at $V_{CC} = 5.0$ V and $T_A = 25°C$.
2. t_{PD} is tested with switch S_1 closed and $C_L = 50$ pF.
3. For three-state outputs, output enable times are tested with $C_L = 50$ pF to the 1.5 V level; S_1 is open for high impedance to HIGH tests and closed for high impedance to LOW tests. Output disable times are tested with $C_L = 5$ pF. HIGH to high impedance tests are made to an output voltage of $V_{OH} - 0.5$ V with S_1 open; LOW to high impedance tests are made to the $V_{OL} + 0.5$ V level with S_1 closed.

Switching Test Circuit

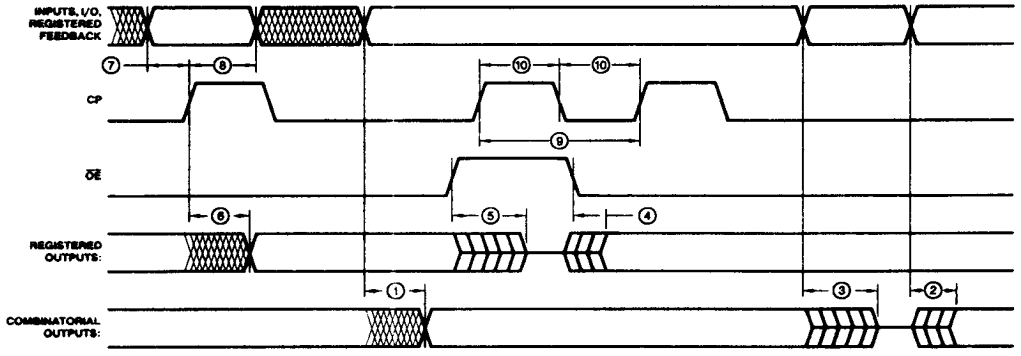


Note: C_1 and C_2 are to bypass V_{CC} to ground.

TEST OUTPUT LOADS		
Pin Name	**Commercial**	**Military**
R_1	200 Ω	390 Ω
R_2	390 Ω	750 Ω
C_1	1 μF	1 μF
C_2	0.1 μF	0.1 μF
C_L	50 pF	50 pF

5

Switching Waveforms



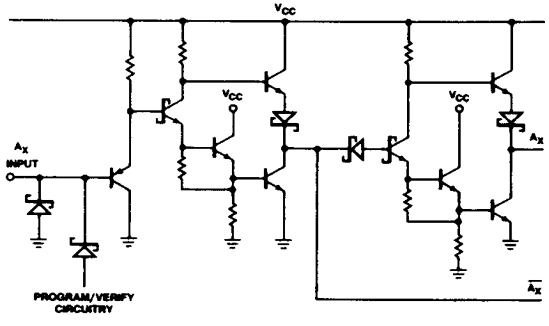
WF002571

Key to Timing Diagram

WAVEFORM	INPUTS	OUTPUTS
	MUST BE STEADY	WILL BE STEADY
	MAY CHANGE FROM H TO L	WILL BE CHANGING FROM H TO L
	MAY CHANGE FROM L TO H	WILL BE CHANGING FROM L TO H
	DON'T CARE; ANY CHANGE PERMITTED	CHANGING; STATE UNKNOWN
	DOES NOT APPLY	CENTER LINE IS HIGH IMPEDANCE "OFF" STATE

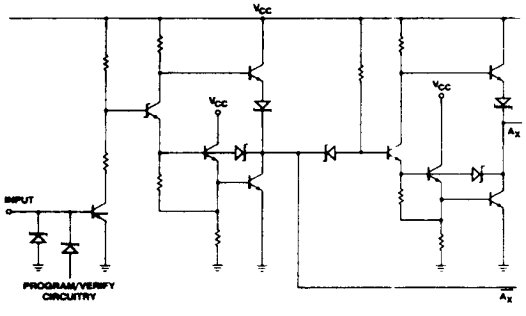
KS000010

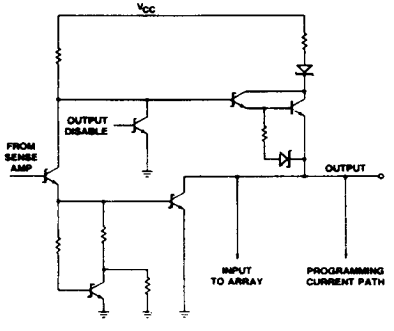
Input Circuitry



IC000720

Output Circuitry





IC000801

Security Fuse Programming

A single fuse is provided on each device to prevent unauthorized copying of PAL fuse patterns. Once blown, the circuitry enabling fuse verification and registered output PRELOAD is permanently disabled.

Programming of the security fuse is the same as an array fuse. Verification of a blown security fuse is accomplished by verifying the whole fuse array as if every fuse is blown.

Programmers/Development Systems

(refer to Programmer Reference Guide, page 3-81)